

A

A

B

B

C

C

D

D

[illegible]

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Layer	Name	Material	Thickness	Constant	Board Layer	Stack
	Top Overlay					
	Top Solder	Solder Resist	0.40mil	3.5		
1	Top Layer		1.40mil			
	Dielectric 1	FR408HR	5.00mil	3.62		
2	L2 GND	CF-004	1.40mil			
	Dielectric 3	FR408HR	3.20mil	3.46		
3	L3 PWR	CF-004	1.40mil			
	Dielectric 5	FR408HR	3.00mil	3.6		
4	L4 GND	CF-004	1.40mil			
	Dielectric 7	FR408HR	9.20mil	3.68		
5	L5 SIG	CF-004	1.40mil			
	Dielectric1	FR408HR	6.40mil	3.46		
6	L6 GND	CF-004	1.40mil			
	Dielectric 8	FR408HR	9.20mil	3.68		
7	L7 GND	CF-004	1.40mil			
	Dielectric 6	FR408HR	3.00mil	3.6		
8	L8 PWR	CF-004	1.40mil			
	Dielectric 4	FR408HR	3.20mil	3.46		
9	L9 GND	CF-004	1.40mil			
	Dielectric 2	FR408HR	5.00mil	3.62		
10	Bottom Layer		1.40mil			
	Bottom Solder	Solder Resist	0.40mil	3.5		
	Bottom Overlay					

Total board thickness:	62.00mil
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**M10 Fab Notes**

**DESIGN INFORMATION**

MIN. TRACK WIDTH: 4 MIL  
 MIN. CLEARANCE: 5 MIL  
 MIN. VIA PAD SIZE: 18 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
 PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL + 5 MIL, HOLES + 3 MIL  
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): + 3 MIL

MATERIAL: ☐ HYBRID STACKUP ☒ UNIFORM STACKUP

☒ ISOLA FR408HR  
☐ Megtron 4 **OR** Isola I-Speed  
☐ Megtron6 **OR** Isola MT-40 **OR** Nelco MW-1000  
☐ OTHER \_\_\_\_\_

THICKNESS: ☒ 62 MIL (1.6mm) + - 10% ☐ OTHER 92 MIL + - 10%  
 TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER + - \_\_\_\_\_

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER + - \_\_\_\_\_

DRILLING:  
 REFERENCE: ☒ AS SHOWN ☐ NC\_DRILL FILES  
 PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER \_\_\_\_\_

BOARD FINISH:  
 SILKSCREEN: ☒ TOP ☒ BOTTOM  
 SILKSCREEN COLOR: ☒ WHITE ☐ OTHER \_\_\_\_\_  
 SOLDER RESIST COLOR: ☐ GREEN ☒ OTHER RED  
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENEPG  
☐ IMM. TIN/SILVER OR EQUIV ☐ HARD GOLD (30u)  
☐ OTHER \_\_\_\_\_

ARRAY/PANEL: ☒ CUT AND TRM PER M1 BOARD OUTLINE  
☐ N.C. ROUTE ☐ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs  
 TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.  
 PCB MUST BEAR THE UL94-V0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:  
 MICROSECTION: ☐ YES  
 BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

## FAB INSTRUCTIONS

- ☒ 16 MIL & SMALLER VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
- ☒ TOP LAYER TRACKS 9.7 MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
- ☐ OUTER LAYER TRACKS XX MIL WIDE WITH XX MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE
- ☐ INNER LAYER XX & XX TRACKS XX MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
- ☐ INNER LAYER TRACKS XX MIL WIDE WITH XX MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE
- ☐ NO PULL-BACK ON COPPER FEATURES TO EDGE OF THE BOARD



PROJECT TITLE:  
ADC3644EVM

DESIGNED FOR:  
Public Release

FILE NAME:  
ADC3644EVM.PcbDoc

ENGINEER:  
GBR

LAYOUT BY:  
GBR

ALTUM DESIGNER VERSION:  
24.7.2.38

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